

9.2 Sub C1

9. (Amended) A heater chip assembly for use in an ink jet printhead, said heater chip assembly including:

a heater chip including a backside having at least one cavity; and

adhesive substantially entirely disposed within said at least one cavity, said adhesive

5 configured for adhering said backside of said heater chip to a substrate.

15.2 Sub C1

15. (Amended) A method of assembling an ink jet printhead, said method comprising the steps of:

micromachining at least one cavity in a backside of a heater chip; and

adhering said backside of said heater chip to a substrate such that adhesive is at least partially

5 disposed within said at least one cavity.

17.2 Sub C1

17. (Amended) The method of claim 15, wherein said micromachining step includes cutting said at least one cavity into said heater chip.

# REMARKS

Claims 1-21 are pending and rejected in this application. Claims 1, 9, 15 and 17 are amended hereby; and claims 16 and 18 are canceled hereby.

Responsive to the rejection of claim 5 under 35 U.S.C. § 112, second paragraph, Applicants respectfully submit that the phrase "said at least one via comprises a plurality of vias" indicates that the at least one via is in the form of more than one via, rather than just one via. Thus, the term "at least one via" is narrowed to exclude the possibility of there being just one via. Applicants submit that claim 5 is allowable in its present form.

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